



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SURFBOARDS®



THE BREADBOARDING MEDIUM FOR **SURFACE MOUNT™**

33000 SERIES APPLICATION SPECIFIC ADAPTERS

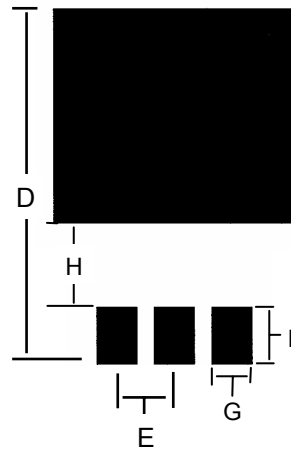
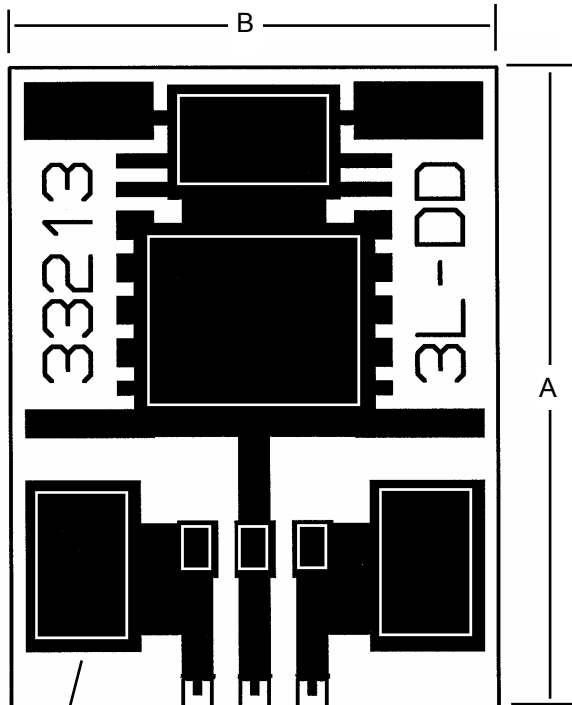
IDS33213

REV 1-2012

MODEL **33213**

FOR TO-263AB 3-LEAD D PACKAGE

HIGHER CURRENT APPLICATIONS



DEVICE MOUNTING FOOTPRINT

PINS PROVIDE INSTRUMENT CONNECTION POINTS. LARGE LANDS CAN BE CLIPPED ONTO OR SOLDERED TO FOR HIGHER CURRENT APPLICATIONS.

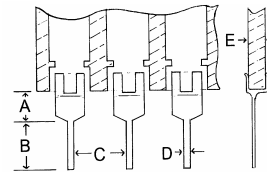
LARGE CIRCUIT LANDS PROVIDE CLIP TO, OR SOLDER TO CONNECTION POINTS FOR HIGHER CURRENT APPLICATIONS

SINGLE-IN-LINE (SIP) PINS PROVIDE INSTRUMENTATION CONNECTIONS

NOTE: CIRCUIT FOILS OR PINS MAY NOT BE SUITABLE FOR HIGHER RATED CURRENT OPERATION. EXTREME TEMPERATURE RISE MAY CAUSE FAILURE.



PIN SPECIFICATIONS / TOLERANCES



In Inches
 A = .062 +/- .006
 B = .130 +/- .010
 C = .100 +/- .005
 D = .020 +/- .004
 E = .031 +/- .005

FIG.	INCHES	MM
A	1.125	28.57
B	.850	21.59
C	.100	2.54
D	.625	15.87
E	.100	2.54
F	.100	2.54
G	.070	1.77
H	.150	3.81

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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CAPITAL ADVANCED TECHNOLOGIES, INC.

CAROL STREAM, ILLINOIS. USA.

PHONE 630-690-1696

WWW.CapitalAdvanced.Com

FAX 630-690-2498